NPN Epitaxial Planar Transistor

HBN3101S6R

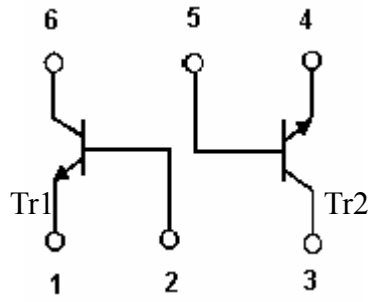
(Dual Transistors)

Features

- Two BF422 chips in a SOT-363 package.
- Mounting possible with SOT-323 automatic mounting machines.
- Transistor elements are independent, eliminating interference.
- Mounting cost and area can be cut in half.
- High BV_{CEO}, $BV_{CEO} \geqq 300V$
- Pb-free lead plating and halogen-free package.

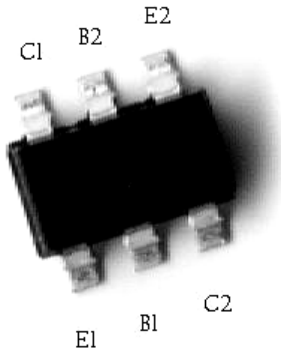
Equivalent Circuit

HBN3101S6R



Outline

SOT-363



Ordering Information

Device	Package	Shipping
HBN3101S6R-0-T1-G	SOT-363 (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel

Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, T1 : 3000 pcs / tape & reel, 7" reel

Product rank, zero for no rank products

Product name

The following characteristics apply to both Tr1 and Tr2

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	300	V
Collector-Emitter Voltage	V_{CEO}	300	V
Emitter-Base Voltage	V_{EBO}	5	V
Collector Current (DC)	I_C	100	mA
Collector Current (Pulse)	I_{CP}	300 (Note 1)	mA
Power Dissipation	Pd	200 (total) (Note 2)	mW
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55~+150	°C

Note : 1.Single pulse, Pw=10ms
2.150mW per element must not be exceeded.

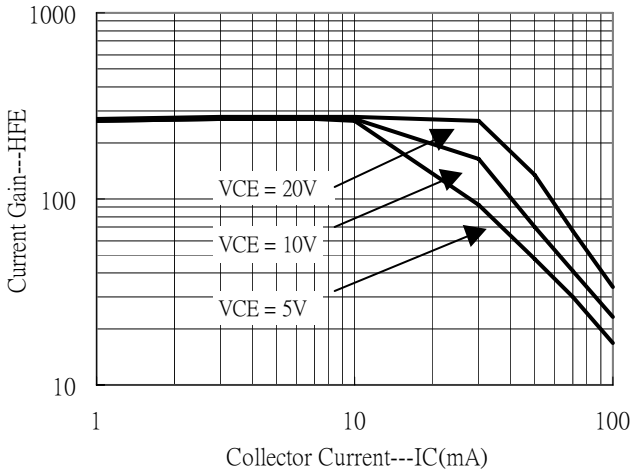
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	300	-	-	V	I_C=100μA
BV_{CEO}	300	-	-	V	I_C=1mA
BV_{EBO}	5	-	-	V	I_E=10μA
I_{CBO}	-	-	100	nA	I_E=0, V_{CB}=300V
I_{EBO}	-	-	100	nA	V_{EB}=5V, I_C=0
*$V_{CE(sat)}$	-	-	300	mV	I_C=30mA, I_B=3mA
*$V_{BE(sat)}$	-	-	900	mV	I_C=30mA, I_B=3mA
*$h_{FE}1$	100	-	250	-	V_{CE}=5V, I_C=10mA
*$h_{FE}2$	15	-	-	-	V_{CE}=5V, I_C=50mA
f_T	60	-	-	MHz	V_{CE}=10V, I_C=10mA, f=100MHz
Cob	-	-	15	pF	V_{CB}=10V, f=1MHz

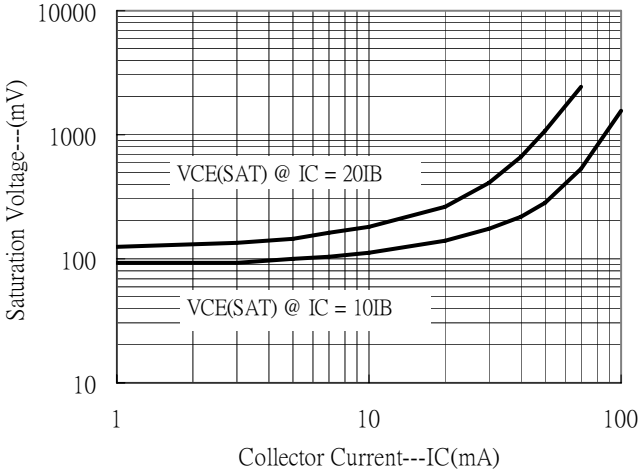
*Pulse Test : Pulse Width ≤380μs, Duty Cycle≤2%

Typical Characteristics

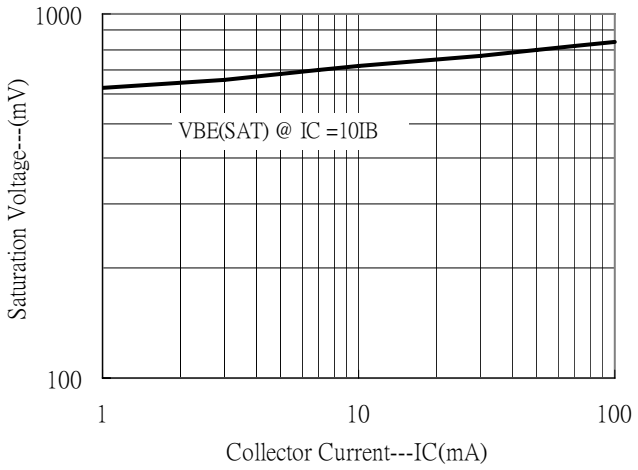
Current Gain vs Collector Current



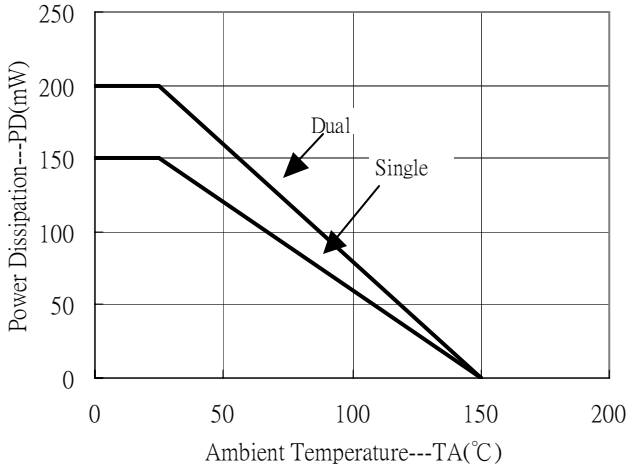
Saturation Voltage vs Collector Current



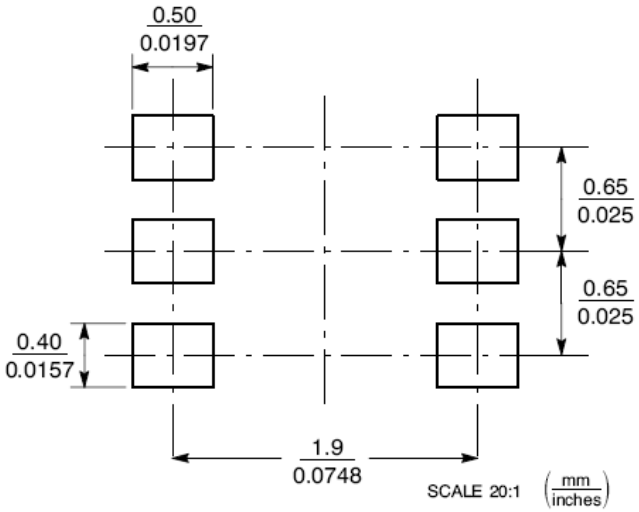
Saturation Voltage vs Collector Current



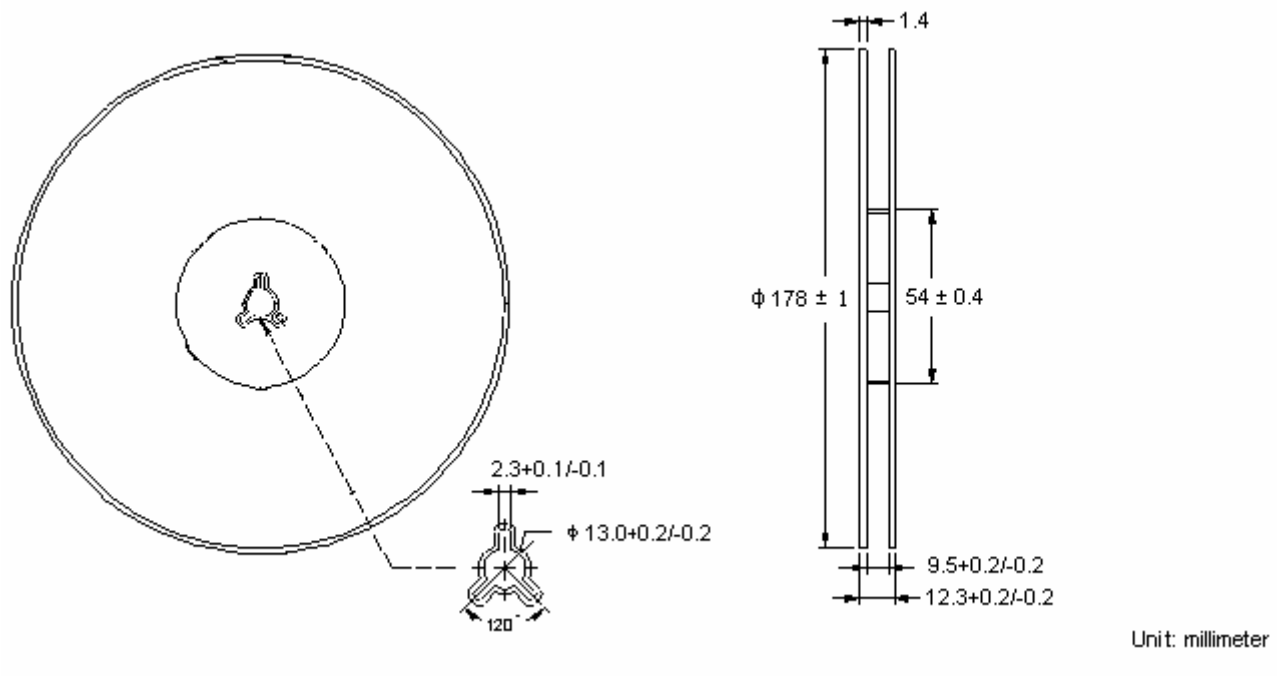
Power Derating Curves



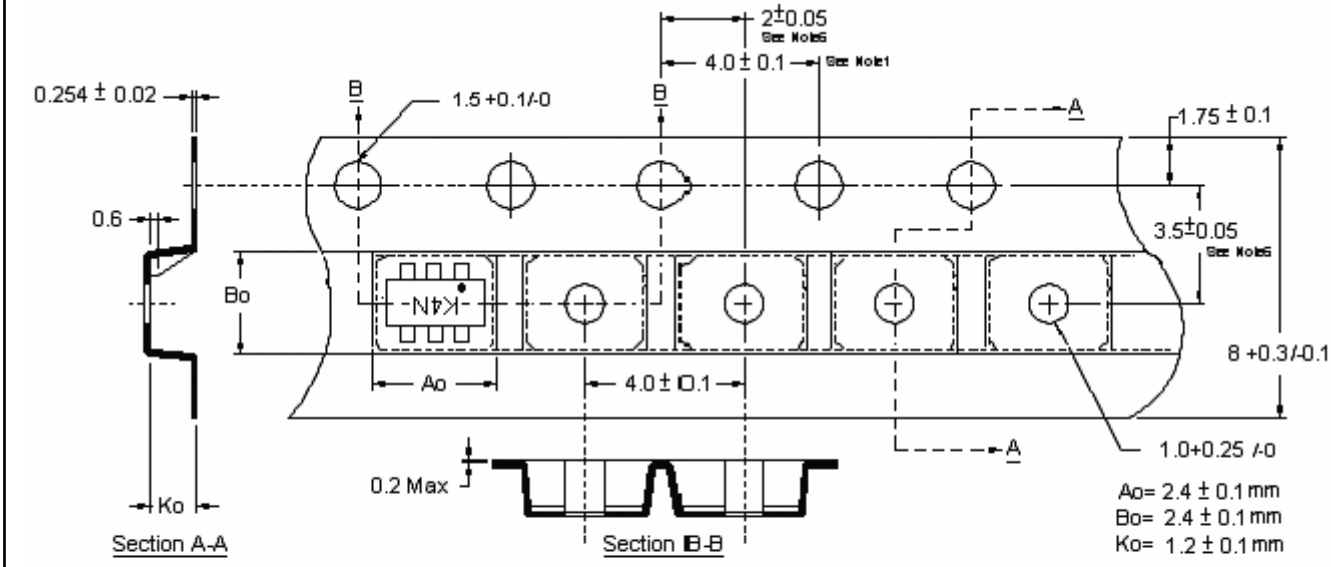
Recommended Soldering Footprint



Reel Dimension



Carrier Tape Dimension



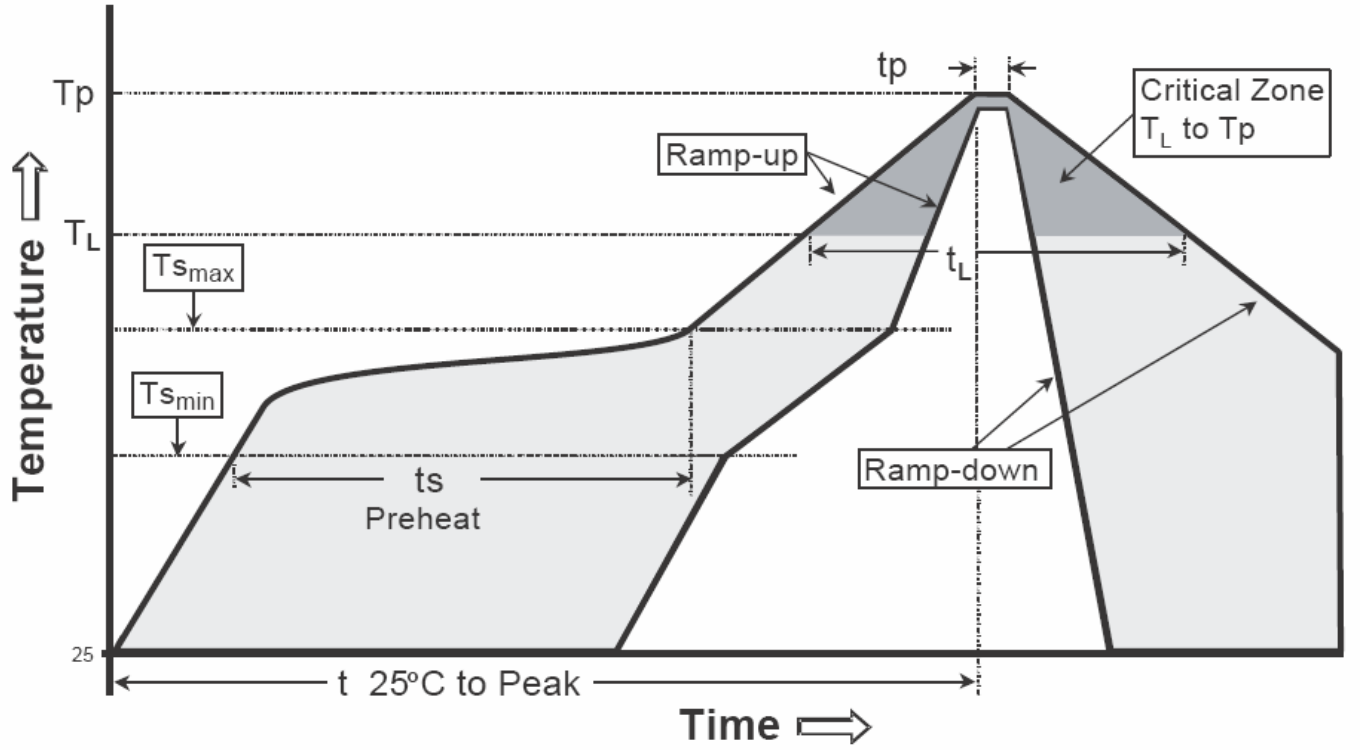
Notes:
1. 10 sprocket hole pitch cumulative tolerace ±0.2.
2. Camber not to exceed 1mm in 100mm.
3. Material: Conductive Black Polystyrene.
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

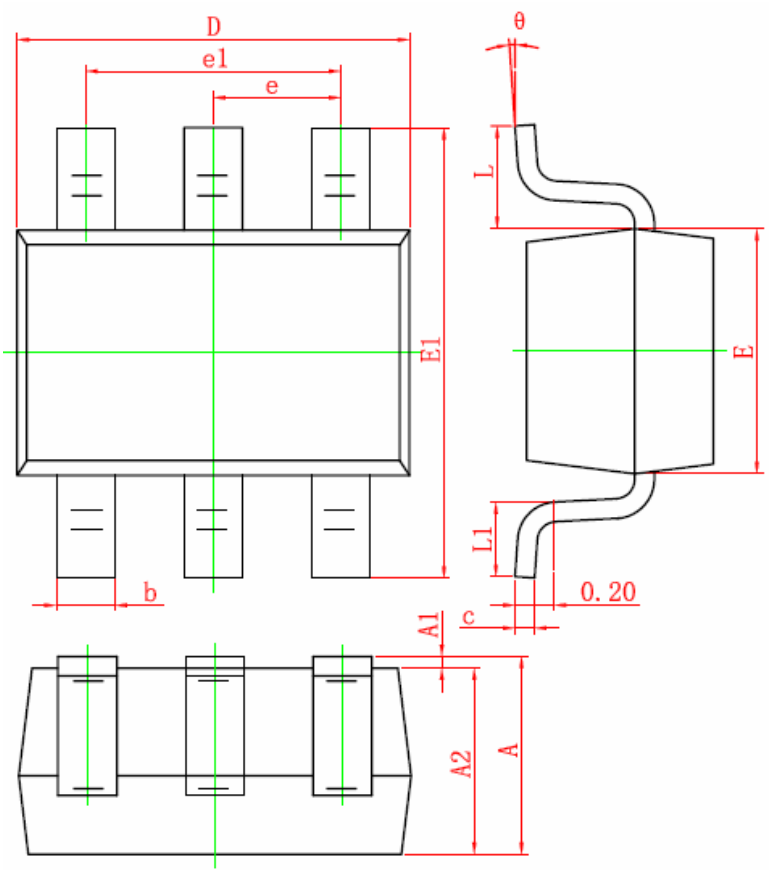
Recommended temperature profile for IR reflow



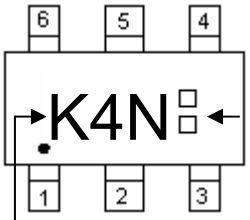
Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(Ts min) −Temperature Max(Ts max) −Time(ts min to ts max)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (TL) − Time (tL)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-363 Dimension



Marking:



Date Code:
Year + Month
Year : 6→2006, 7→2007,…, etc
Month : 1→Jan 2→Feb, …, 9→Sep, A→Oct, B→Nov, C→Dec

Device Code

6-Lead SOT-363 Plastic Surface Mounted Package
CYStek Package Code: S6R

Style:
Pin 1. Emitter1 (E1)
Pin 2. Base1 (B1)
Pin 3. Collector2 (C2)
Pin 4. Emitter2 (E2)
Pin 5. Base2 (B2)
Pin 6. Collector1 (C1)

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043	E1	2.150	2.450	0.085	0.096
A1	0.000	0.100	0.000	0.004	e	0.650 TYP		0.026 TYP	
A2	0.900	1.000	0.035	0.039	e1	1.200	1.400	0.047	0.055
b	0.150	0.350	0.006	0.014	L	0.525 REF		0.021 REF	
c	0.080	0.150	0.003	0.006	L1	0.260	0.460	0.010	0.018
D	2.000	2.200	0.079	0.087	θ	0°	8°	0°	8°
E	1.150	1.350	0.045	0.053					

Notes : 1.Controlling dimension : millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : Pure tin plated.
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0.